

<DIODE Modules>

RM800DY-34S

HIGH POWER SWITCHING USE
INSULATED TYPE



dual pack

Forward current I_{DC} **800 A**
 Repetitive peak reverse voltage V_{RRM} **1700 V**
 Maximum junction temperature T_{vjmax} **175 °C**

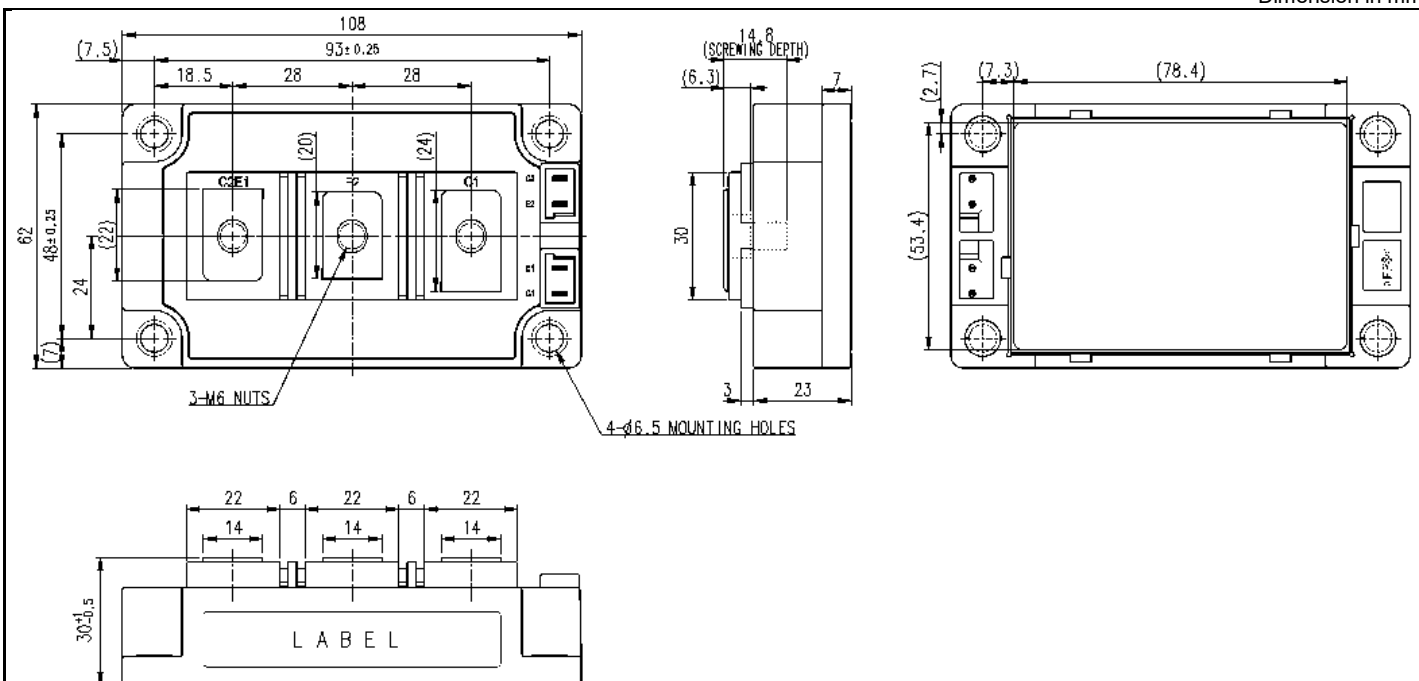
- Flat base Type
- Copper base plate
- RoHS Directive compliant
- UL Recognized under UL1557, File No. E323585

APPLICATION

AC Motor Control, Motion/Servo Control, Power supply, Photovoltaic power, Wind power, etc.

OUTLINE DRAWING & INTERNAL CONNECTION

Dimension in mm



INTERNAL CONNECTION



Terminal code

C2E1 : A2
 E2 : A1K2
 C1 : K1

Tolerance otherwise specified

| Division of Dimension | Tolerance |
|-----------------------|-----------|
| 0.5 to 3 | ±0.2 |
| over 3 to 6 | ±0.3 |
| over 6 to 30 | ±0.5 |
| over 30 to 120 | ±0.8 |
| over 120 to 400 | ±1.2 |
| over 400 to 1000 | ±2.0 |
| over 1000 to 2000 | ±3.0 |
| over 2000 to 4000 | ±4.0 |

RM800DY-34SHIGH POWER SWITCHING USE
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| Symbol | Item | Conditions | Rating | Unit |
|-------------|--------------------------------------|--|-------------------|--------------------|
| V_{RRM} | Repetitive peak reverse voltage | - | 1700 | V |
| V_{RSM} | Non-repetitive peak reverse voltage | - | 1700 | V |
| $V_{R(DC)}$ | Reverse DC blocking voltage | - | 1360 | V |
| I_{DC} | Forward current | DC (Note1) | 800 | A |
| I_{FSM} | Surge non-repetitive forward current | 1 cycle of half wave at 60 Hz, peak value, $T_{vj}=25\text{ }^{\circ}\text{C}$ start, $V_{RM}=0\text{ V}$ | 4000 | A |
| I^2t | Current square time for fusing | $t_w=8.3\text{ ms}$, $T_{vj}=25\text{ }^{\circ}\text{C}$ start, Value for one cycle of surge current | 6.0×10^4 | A ² s |
| V_{isol} | Isolation voltage | Terminals to base plate, RMS, f=60 Hz, AC 1 min | 4000 | V |
| T_{vjmax} | Maximum junction temperature | Instantaneous event (overload) | 175 | $^{\circ}\text{C}$ |
| T_{Cmax} | Maximum case temperature | (Note2) | 125 | |
| T_{vjop} | Operating junction temperature | Continuous operation (under switching) | -40 ~ +150 | $^{\circ}\text{C}$ |
| T_{stg} | Storage temperature | - | -40 ~ +125 | |

ELECTRICAL CHARACTERISTICS ($T_{vj}=25\text{ }^{\circ}\text{C}$, unless otherwise specified)

| Symbol | Item | Conditions | Limits | | | Unit |
|---------------------|-----------------------------------|---|--------------------------------------|------|------|---------------|
| | | | Min. | Typ. | Max. | |
| I_{RRM} | Reverse current | $V_R=V_{RRM}$, $T_{vj}=150\text{ }^{\circ}\text{C}$ | - | - | 50 | mA |
| V_F (Terminal) | Forward voltage | $I_F=800\text{ A}$, $t_w \leq 1\text{ ms}$, Refer to the figure of test circuit | $T_{vj}=25\text{ }^{\circ}\text{C}$ | 2.25 | 2.75 | V |
| | | | $T_{vj}=125\text{ }^{\circ}\text{C}$ | 2.35 | - | |
| | | | $T_{vj}=150\text{ }^{\circ}\text{C}$ | 2.30 | - | |
| V_F (Chip) | | $I_F=800\text{ A}$, $t_w \leq 1\text{ ms}$ | - | 2.00 | 2.50 | V |
| t_{rr} | Reverse recovery time | $V_{CC}=1000\text{ V}$, $I_F=800\text{ A}$, | - | - | 500 | ns |
| Q_{rr} | Reverse recovery charge | $-diF/dt=4000\text{ kA}/\mu\text{s}$, | - | 160 | - | μC |
| E_{rr} | Reverse recovery energy per pulse | Inductive load | - | 104 | - | mJ |

THERMAL RESISTANCE CHARACTERISTICS

| Symbol | Item | Conditions | Limits | | | Unit |
|---------------|----------------------------|--|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| $R_{th(j-c)}$ | Thermal resistance | Junction to case (Note2) | - | - | 20 | K/kW |
| $R_{th(c-s)}$ | Contact thermal resistance | Case to heat sink, Thermal grease applied (Note2, 4) | - | 13.3 | - | K/kW |

MECHANICAL CHARACTERISTICS

| Symbol | Item | Conditions | Limits | | | Unit |
|--------|------------------------|---------------------------------|--------|------|------|---------------|
| | | | Min. | Typ. | Max. | |
| M_t | Mounting torque | Main terminals M 6 screw | 3.5 | 4.0 | 4.5 | N·m |
| M_s | Mounting torque | Mounting to heat sink M 6 screw | 3.5 | 4.0 | 4.5 | N·m |
| d_s | Creepage distance | Terminal to terminal | - | - | - | mm |
| | | Terminal to base plate | - | - | - | |
| d_a | Clearance | Terminal to terminal | - | - | - | mm |
| | | Terminal to base plate | - | - | - | |
| e_c | Flatness of base plate | On the centerline X, Y (Note5) | 0 | - | +200 | μm |
| m | mass | - | - | 260 | - | g |

*: This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU.

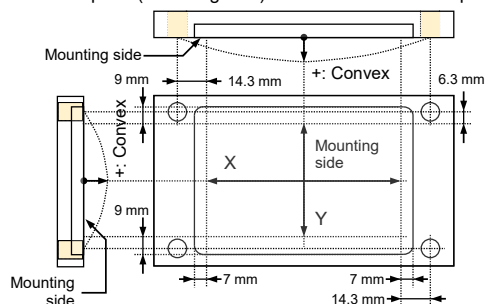
Note1. Junction temperature (T_{vj}) should not exceed T_{vjmax} rating.

2. Case temperature (T_c) and heat sink temperature (T_s) are defined on the each surface (mounting side) of base plate and heat sink just under the chips.
Refer to the figure of chip location.

3. Pulse width and repetition rate should be such as to cause negligible temperature rise. Refer to the figure of test circuit.

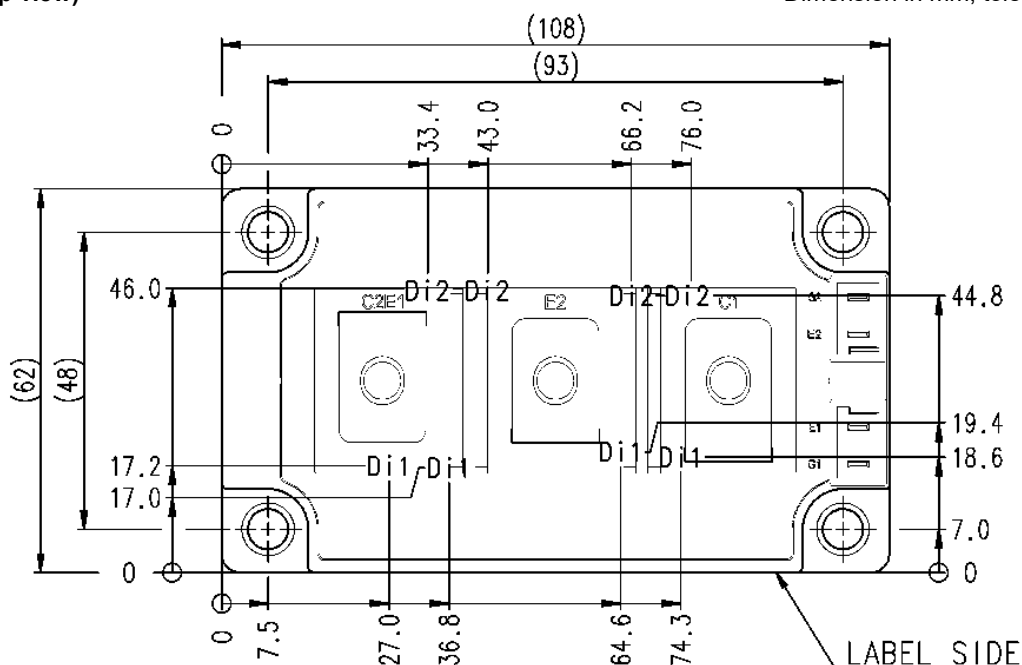
4. Typical value is measured by using thermally conductive grease of $\lambda=3.0 \text{ W/(m}\cdot\text{K)}/D_{(C-S)}=50 \text{ }\mu\text{m}$.

5. The base plate (mounting side) flatness measurement points (X, Y) are shown in the following figure.

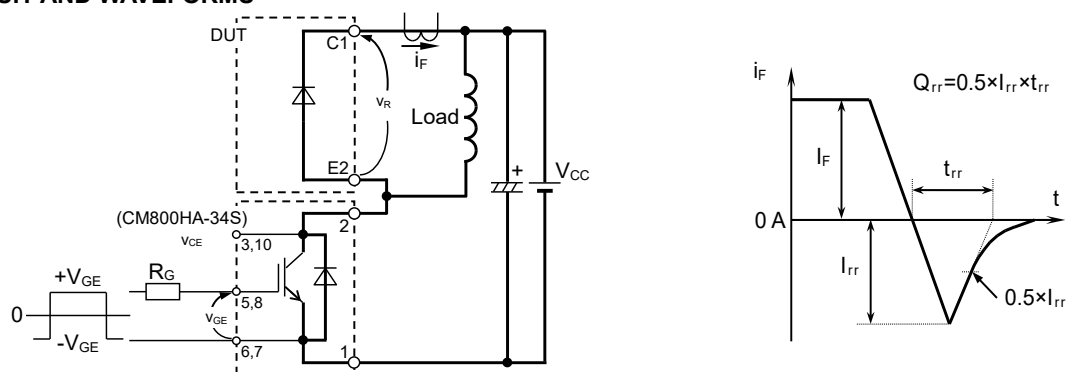


CHIP LOCATION (Top view)

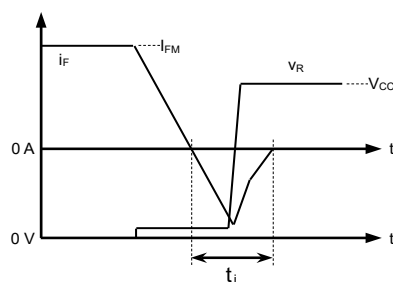
Dimension in mm, tolerance: $\pm 1 \text{ mm}$



TEST CIRCUIT AND WAVEFORMS

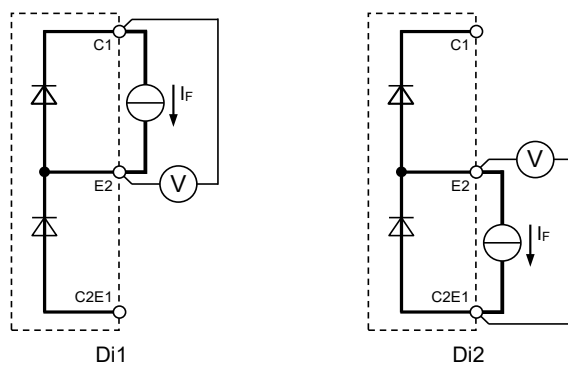


t_{rr} , Q_{rr} characteristics test circuit and waveforms

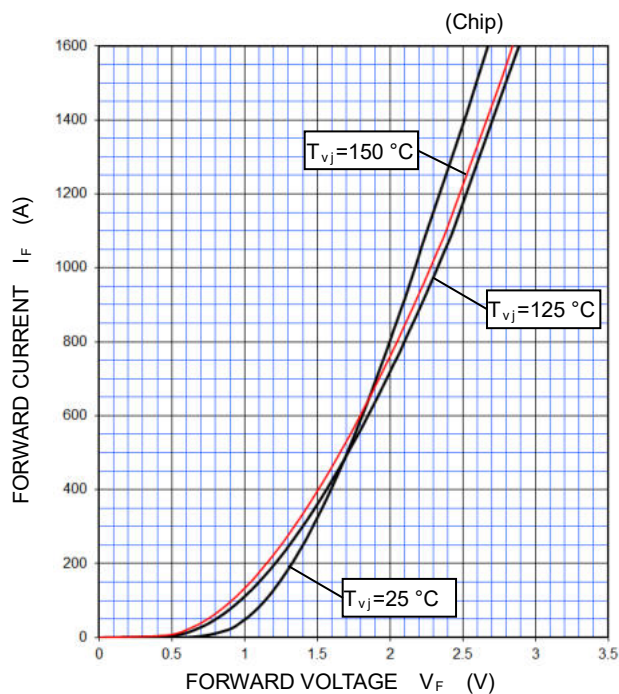
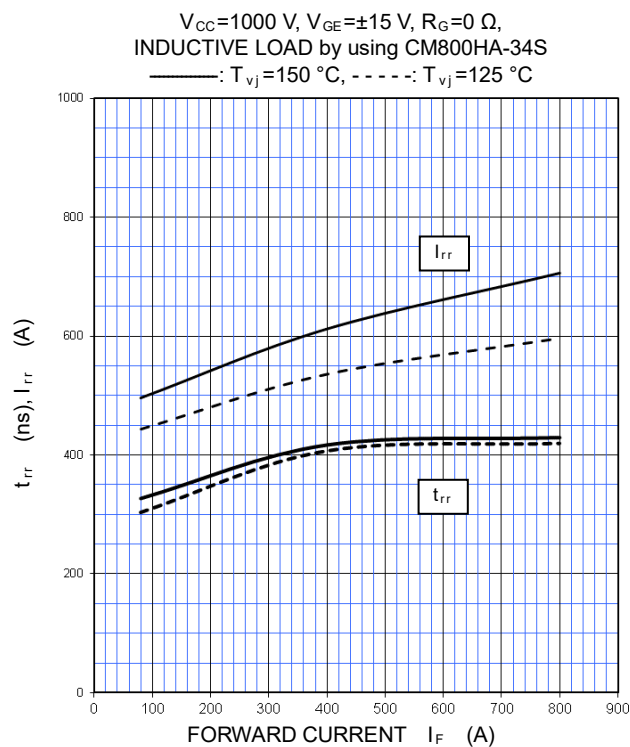
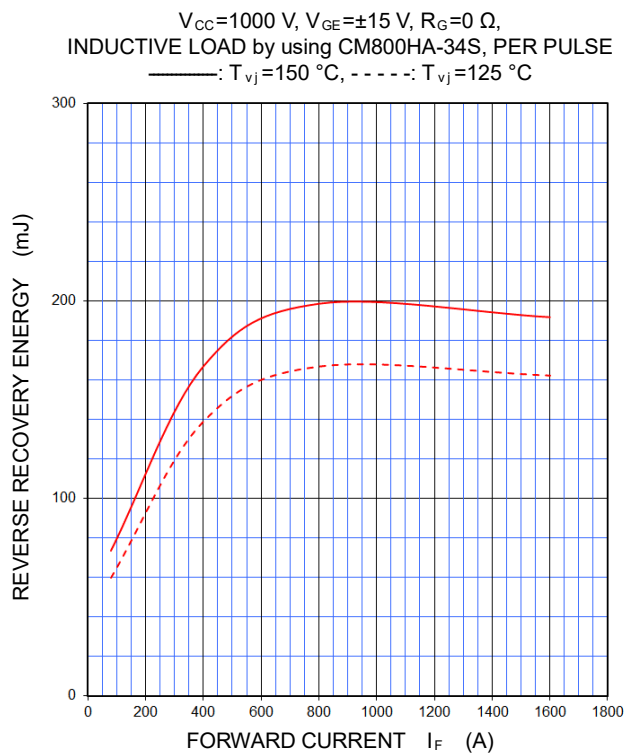
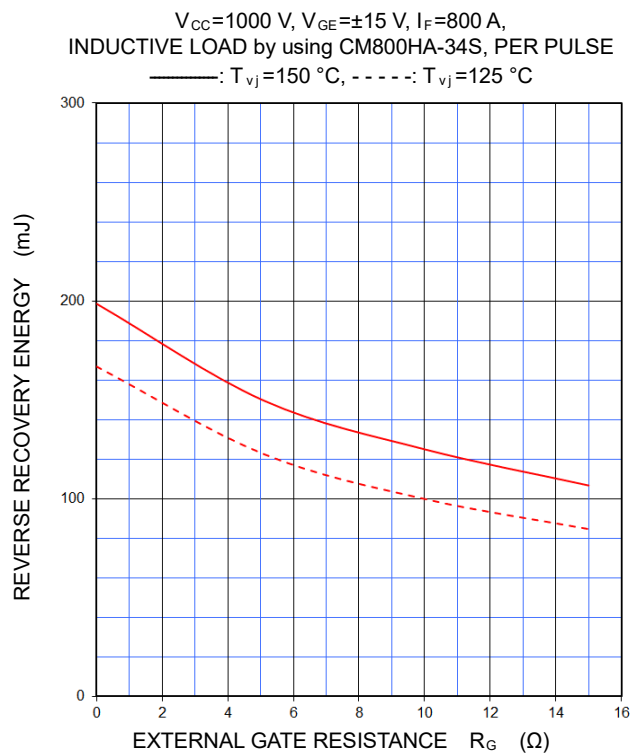


Reverse recovery energy test waveforms (Integral time instruction drawing)

TEST CIRCUIT



V_F characteristics test circuit

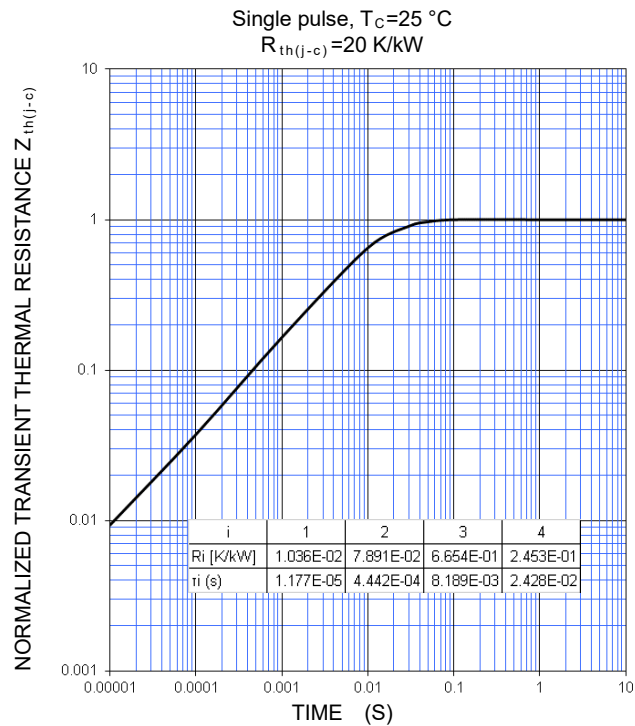
PERFORMANCE CURVES**FORWARD CHARACTERISTICS
(TYPICAL)****REVERSE RECOVERY CHARACTERISTICS
(TYPICAL)****HALF-BRIDGE SWITCHING CHARACTERISTICS
(TYPICAL)****HALF-BRIDGE SWITCHING CHARACTERISTICS
(TYPICAL)**

RM800DY-34S

HIGH POWER SWITCHING USE
INSULATED TYPE

PERFORMANCE CURVES

TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS
(MAXIMUM)



Note: The characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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